ON Semiconductor

Initial Product/Process Change Notification

Document # : IPCN20626XF
Issue Date: 3 June 2015

Title of Change:	Initial PCN for wire change from gold to copper, mold compound change and part number change.
Proposed first ship date:	10 October 2015
Contact information:	Contact your local ON Semiconductor Sales Office or < Yasuhiro Igarashi @onsemi.com >
Samples:	Contact your local ON Semiconductor Sales Office.
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with new part number (changing suffix to "-W").

PART_ID	New Part_ID
VEC2315-TL-H	VEC2315-TL-W
VEC2415-TL-E	VEC2415-TL-W
VEC2616-TL-H	VEC2616-TL-W
VEC2616-TL-H-Z	VEC2616-TL-W-Z

Change category(s):

☐ Wafer Fab Change
☐ Assembly Change
☐ Test Change
☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☒ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:	Site 1	Site 2
☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ☐ External Foundry/Subcon site(s):	ON Shenzhen, China	

Description and Purpose:

This is an Initial Process Change Notification to announce the contents below.

1) Changing wire material from gold to copper
2) Changing part number from XXXXXXX-TL-E, XXXXXXX-TL-H and XXXXXXX-TL-H-Z to XXXXXXX-TL-W and XXXXXXX-TL-W-Z.
3) Changing mold compound from halide to halide free.

Qualification Plan:

Estimated date for qualification completion: 18 June 2015

Test	Conditions	Results
Steady State Operating Life	Tj=150degC	1000 hrs.
High Temperature Reverse Bias	Ta=150degC,VR=max	1000 hrs.
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs.
Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles
Pressure Cooker	Ta=121degC,2.03×10^5Pa,100%	50 hrs.
High Temperature Storage	Ta=150degC	1000 hrs.
Resistance to Soldering heat(Reflow)	Solder Temp.:260degC±5degC	10s
Solderability	Solder Temp.: 245degC±5degC	5 s

List of Affected Standard Parts:

VEC2315-TL-H
VEC2415-TL-E
VEC2616-TL-H
VEC2616-TL-H-Z